

Description du produit

La pâte BEST-Solder (Tin) est le meilleur choix de reballing IC.
meilleure marque originale,
Qualité vérifiée

Application: peut être utilisé pour la réparation d'ordinateurs portables / ordinateurs /
téléphones portables / domestiques Appliances SMD IC et BGA IC, outils pour la
pucceréparer et ligne de fabrication électronique.

Paramètre de technologie

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Thématique de référence
: N g W p c

SOLDER PASTE

Lead-free High temperature



500g

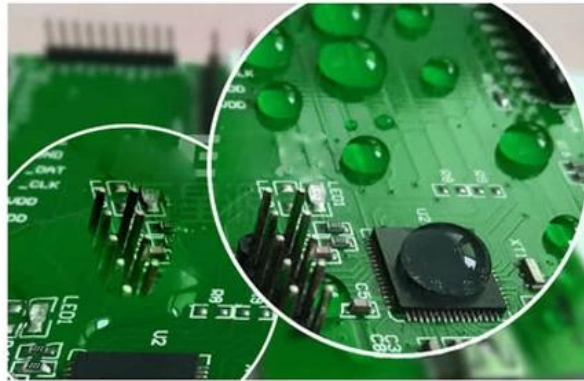
Low residue / Rapid welding / lead free / Solder spot bright / Ag

Product Usage

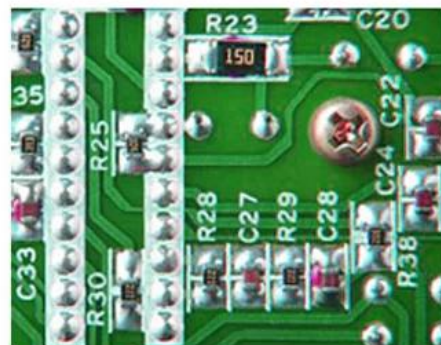
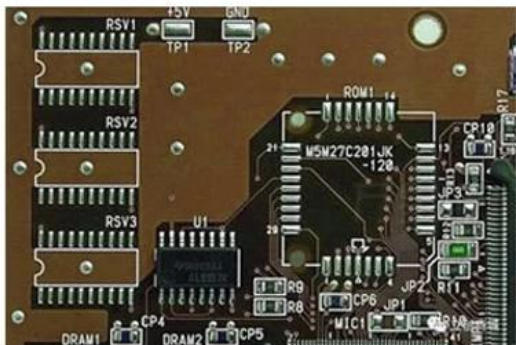


MODEL	BST-705
SHELF LIFE	6 months
INGREDIENT	Sn99/Ag0.3/Cu0.7
WEIGHT	500g
MELTING POINT	217°C

Having a large insulation resistance does not corrode the PCB, and the requirements for no-cleaning can be achieved.



High impedance, full and bright solder, low residue

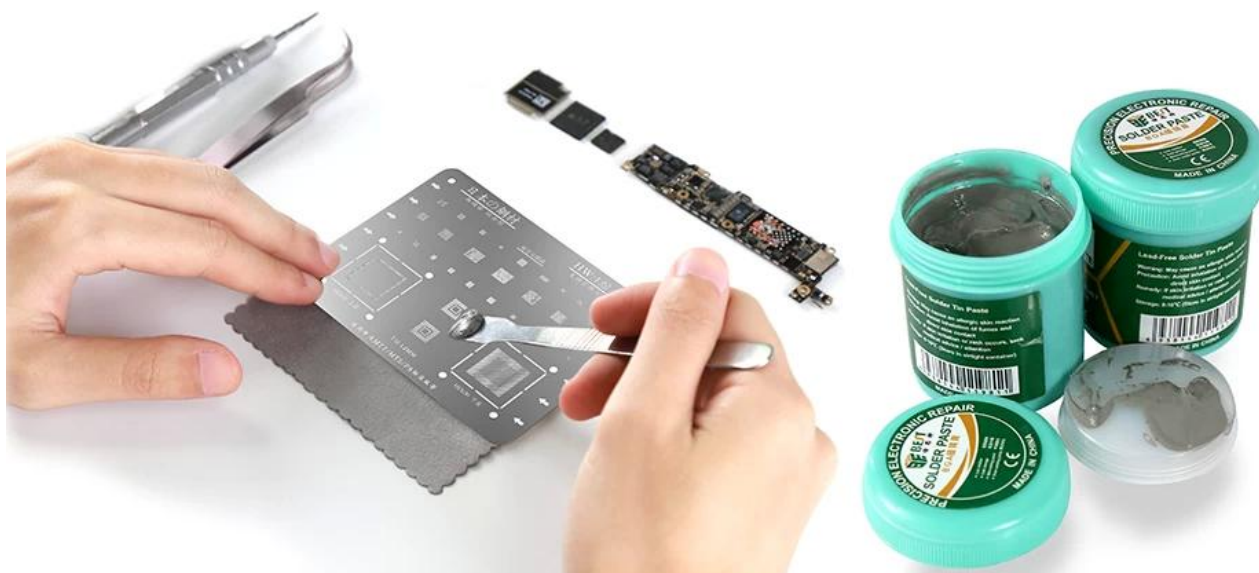


Welding requirements for a wide range of products



TESTING EFFECT

UNIFORM SOLDER JOINT
MEDIUM TEMPERATURE MELTING POINT



PRODUCT SIZE



63.0MM



52MM

75MM

